

NOTES UNLESS OTHERWISE SPECIFIED:

- FABRICATE IAW IPC-6012, CLASS 2, CURRENT REVISION.
- BOARD SHALL MEET THE INSPECTION CRITERIA OF IPC-A-600 CLASS 2, CURRENT REVISION.
- USE ARTWORK 1080956AW CURRENT REV.

4 MATERIAL: NELCO N4000-13.

5 FINISHED WEIGHT PER SQUARE FOOT NOMINAL:  
OUTER LAYERS SHALL BE 1 OZ.  
INNER LAYERS SHALL BE 1 OZ.

6. DESMEAR HOLES AND VIAS.

7 FINISH: ELECTROLESS NI IMMERSION AU (ENIG).  
GOLD PLATING THICKNESS TO BE BETWEEN 3 – 8 MICRONS.

8. SILKSCREEN COMPONENT SIDE ONLY WITH NONCONDUCTIVE EPOXY INK. COLOR SHALL BE A CONTRASTING INK WITH RESPECT TO SOLDERMASK COLOR. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. REMOVE EPOXY INK FROM SOLDER LANDS.

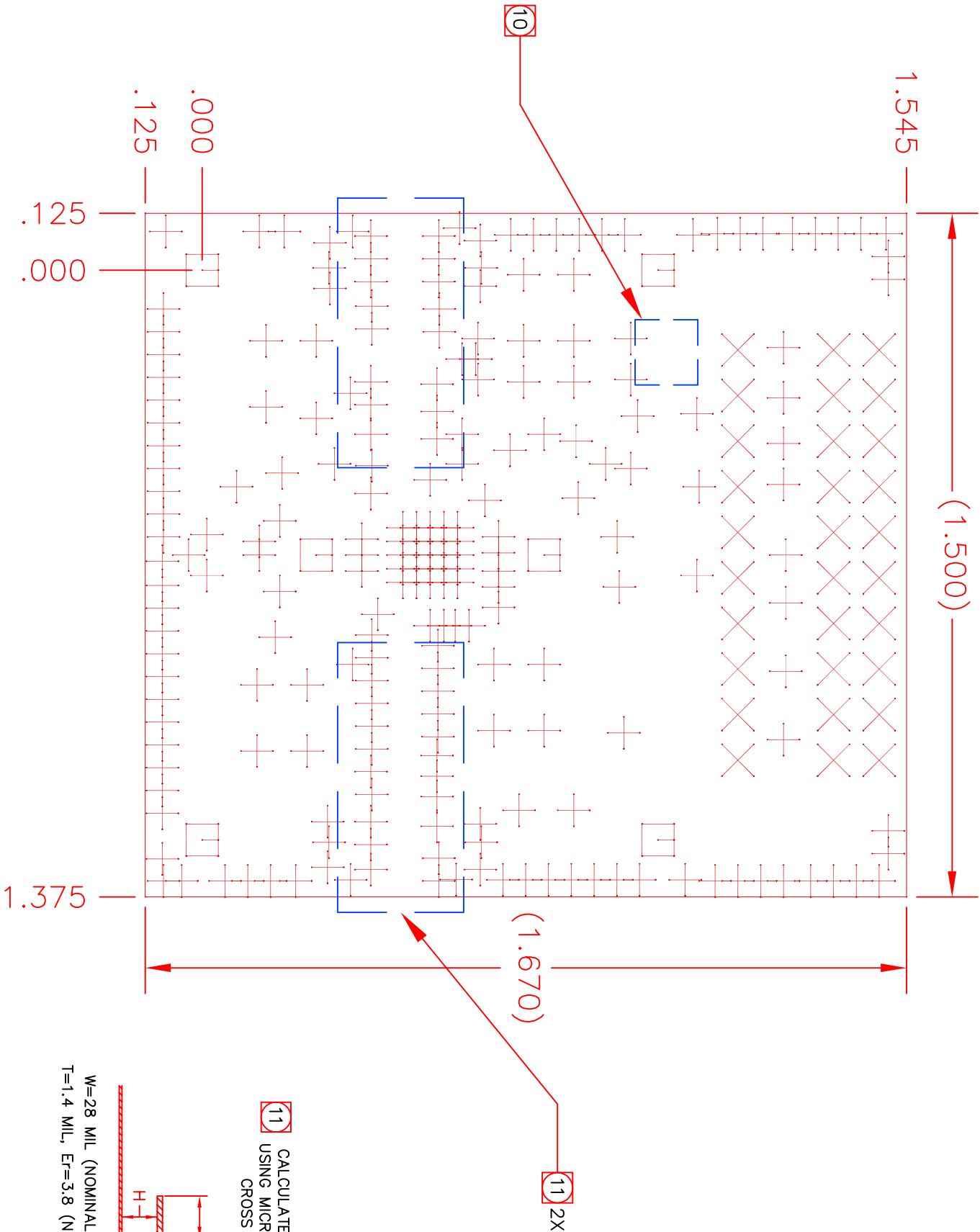
9. APPLY SOLDERMASK OVER BARE COPPER (SMOBC) IAW IPC-SM-840, TOP SIDE ONLY, USING LPI, COLOR CLEAR OR GREEN. SOLDERMASK OVER VIAS IS NOT ACCEPTABLE.

10 SUPPLIER LOT NUMBER/DATE CODE SHALL ONLY BE SILKSCREENED WITH NON-CONDUCTIVE EPOXY INK IN APPROX. LOCATION SHOWN.  
NO LOGO SHALL BE PRINTED.

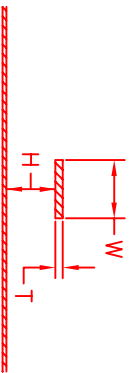
11 CALCULATE IMPEADANCE USING MICROSTRIP MODEL.  
ADJUST RF TRACE WIDTH TO MEET 50 OHMS +/- 5%.

12. INCLUDE A 50 OHM TEST COUPON.

## COMPONENT SIDE



11 CALCULATE IMPEADANCE USING MICROSTRIP MODEL CROSS SECTION



W=28 MIL (NOMINAL), H=14 MIL (NOMINAL)  
T=1.4 MIL, Er=3.8 (NELCO N4000-13 @ 2GHz)

4 LAYER  
CROSS SECTION  
FILM SET

5

LAYER 1 – COMP SIDE  
LAYER 2 – INTERNAL 2  
LAYER 3 – INTERNAL 3  
LAYER 4 – BOTTOM SIDE

PREPREG  
CORE  
PREPREG

1 OZ. CU  
1 OZ. CU  
1 OZ. CU  
1 OZ. CU

4 LAYER  
CROSS SECTION  
DIMENSIONAL TOLERANCE

.062 ± .004

.014 ± .002

.014 ± .002

PREPREG  
CORE  
PREPREG

### HOLE SCHEDULE (ALL PLATED THRU DIAMETERS ARE AFTER PLATING)

SYM	DESCRIPTION	PLATED THRU	QTY
+	Ø.010 +.003/- .010 THRU	YES	226
×	Ø.040 ±.003 THRU	YES	30
□	Ø.102 ±.003 THRU	YES	6

TiQuint SEMICONDUCTOR PROPRIETARY INFORMATION

A

B

1080956PC

C

D